



MOTOROLA
Semiconductors

BOX 20912 • PHOENIX, ARIZONA 85036

The RF Line

NPN SILICON RF POWER TRANSISTOR

... designed primarily for wideband large-signal output amplifier stages in the 100-500 MHz frequency range.

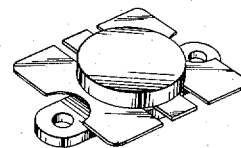
- Guaranteed Performance @ 400 MHz, 28 Vdc
Output Power = 80 Watts over 225-400 MHz Band
Minimum Gain = 7.3 dB @ 400 MHz
- Built-in Matching Network for Broadband Operation Using Double Match Technique
- 100% Tested for Load Mismatch at all Phase Angles with 30:1 VSWR
- Gold Metallization System for High Reliability Applications
- Characterized for 100-500 MHz

MRF327

80 W – 100-500 MHz

CONTROLLED "Q"
BROADBAND RF POWER
TRANSISTOR

NPN SILICON



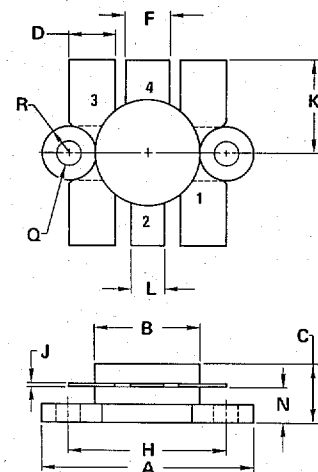
MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V_{CEO}	33	Vdc
Collector-Base Voltage	V_{CBO}	60	Vdc
Emitter-Base Voltage	V_{EBO}	4.0	Vdc
Collector Current – Continuous	I_C	9.0	Adc
– Peak		12.0	
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ (1) Derate above 25°C	P_D	250 1.43	Watts W/ $^\circ\text{C}$
Storage Temperature Range	T_{stg}	-65 to +200	$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	0.7	$^\circ\text{C/W}$

(1) These devices are designed for RF operation. The total device dissipation rating applies only when the devices are operated as RF amplifiers.



STYLE 1:
PIN 1. EMITTER
2. COLLECTOR
3. EMITTER
4. BASE
FLANGE-ISOLATED

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	24.38	25.15	0.960	0.990
B	12.45	12.95	0.490	0.510
C	5.97	7.62	0.235	0.300
D	5.33	5.59	0.210	0.220
F	5.08	5.33	0.200	0.210
H	18.29	18.54	0.720	0.730
J	0.10	0.15	0.004	0.006
K	10.29	—	0.405	—
L	3.81	4.06	0.150	0.160
N	3.81	4.32	0.150	0.170
Q	2.92	3.30	0.115	0.130
R	3.05	3.30	0.120	0.130

CASE 316-01

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted.)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Collector-Emitter Breakdown Voltage ($I_C = 80 \text{ mA dc}, I_B = 0$)	BV_{CEO}	33	—	—	Vdc
Collector-Emitter Breakdown Voltage ($I_C = 80 \text{ mA dc}, V_{BE} = 0$)	BV_{CES}	60	—	—	Vdc
Emitter-Base Breakdown Voltage ($I_E = 8.0 \text{ mA dc}, I_C = 0$)	BV_{EBO}	4.0	—	—	Vdc
Collector-Base Breakdown Voltage ($I_C = 80 \text{ mA dc}, I_C = 0$)	BV_{CBO}	60	—	—	Vdc
Collector Cutoff Current ($V_{CB} = 30 \text{ V dc}, I_E = 0$)	I_{CBO}	—	—	5.0	mA dc

ON CHARACTERISTICS

DC Current Gain ($I_C = 4.0 \text{ A dc}, V_{CE} = 5.0 \text{ V dc}$)	h_{FE}	20	—	80	—
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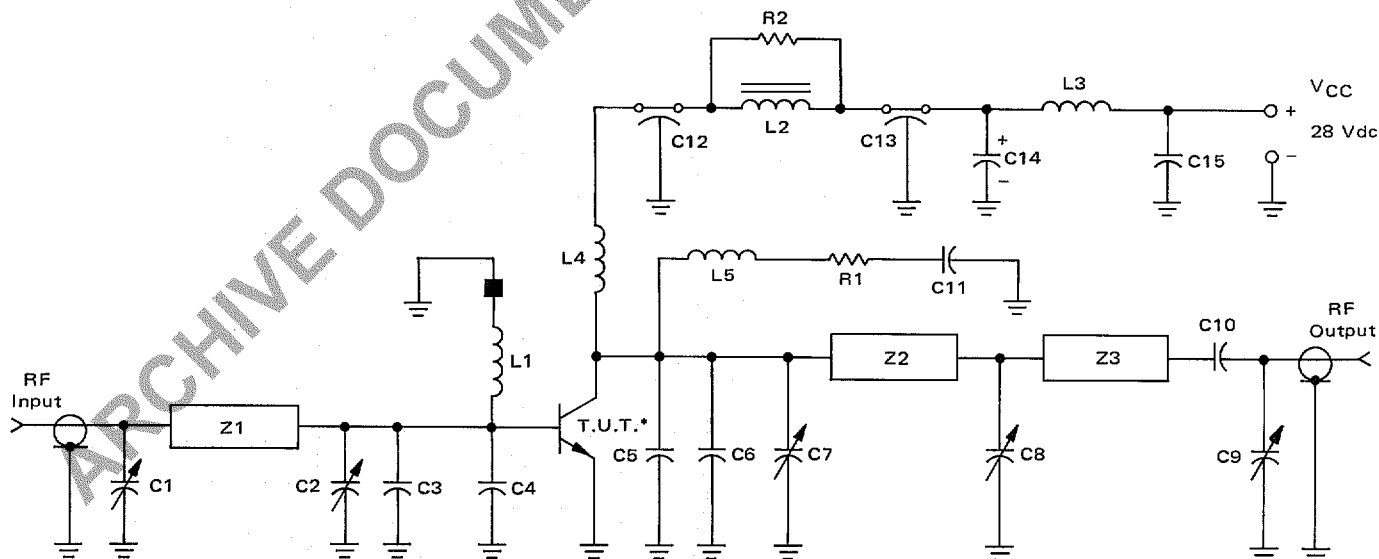
DYNAMIC CHARACTERISTICS

Output Capacitance ($V_{CB} = 28 \text{ V dc}, I_E = 0, f = 1.0 \text{ MHz}$)	C_{ob}	—	100	145	pF
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FUNCTIONAL TESTS (Figure 1)

Common-Emitter Amplifier Power Gain ($V_{CC} = 28 \text{ V dc}, P_{out} = 80 \text{ W}, f = 400 \text{ MHz}$)	G_{PE}	7.3	9.0	—	dB
Collector Efficiency ($V_{CC} = 28 \text{ V dc}, P_{out} = 80 \text{ W}, f = 400 \text{ MHz}$)	η	50	60	—	%
Load Mismatch ($V_{CC} = 28 \text{ V}, P_{out} = 80 \text{ W}, f = 400 \text{ MHz}, \text{VSWR } 30:1$ all phase angles)	ψ	No Degradation in Output Power			

FIGURE 1 — 400 MHz TEST CIRCUIT



- C1, C2, C7, C8, C9 — 1.0-20 pF Piston Trimmer (Johanson JMC 5501)
- C3, C4 — 36 pF ATC 100 mil Chip Capacitor
- C5, C6 — 43 pF ATC 100-mil Chip Capacitor
- C10 — 100 pF UNELCO
- C11, C15 — 0.1 μF Erie Redcap
- C12, C13 — 680 pF Feedthru
- C14 — 1.0 μF 50 V Tantalum
- L1 — 4 Turns #22 AWG Enameled, 3/16" ID Closewound with Ferroxcube Bead (#56-590-65/4B) on Ground End of Coil
- L2 — Ferroxcube VK200-19/4B Ferrite Choke
- L3 — 7 Turns #18 AWG, 11/16" Long, Wound on a 100 k Ω 2 Watt Resistor

- L4 — 6 Turns #20 AWG Enameled, 3/16" ID Closewound
- L5 — 4 Turns #22 AWG Enameled, 1/8" ID Closewound
- Z1 — Microstrip 0.2" W x 1.5" L
- Z2 — Microstrip 0.17" W x 1.16" L
- Z3 — Microstrip 0.17" W x 0.63" L
- R1, R2 — 10 Ω 2 Watt
- Board — Glass Teflon $\epsilon_R = 2.56, t = 0.062"$
- Input/Output Connectors Type N
- T.U.T. Socket Lead Frame Etched from 80 mil Thick Copper
- *Transistor Under Test



FIGURE 2 – POWER GAIN versus FREQUENCY

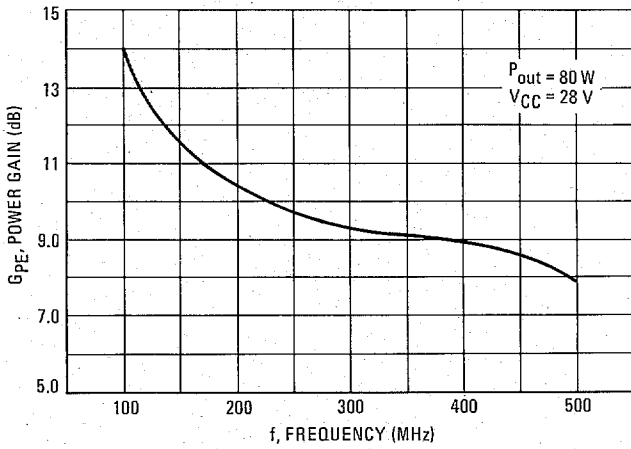


FIGURE 3 – OUTPUT POWER versus FREQUENCY

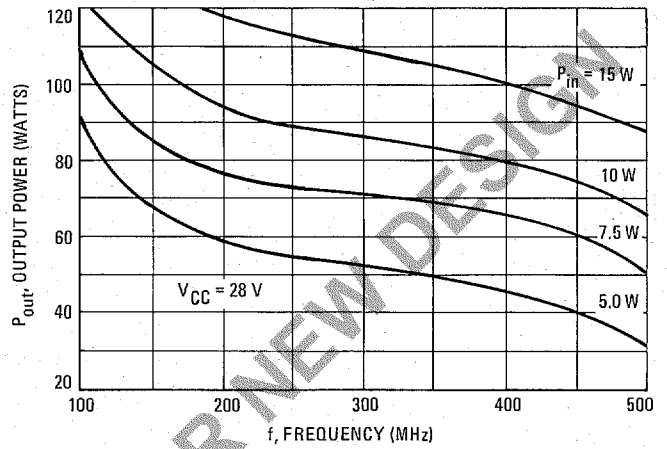


FIGURE 4 – OUTPUT POWER versus SUPPLY VOLTAGE
f = 225 MHz

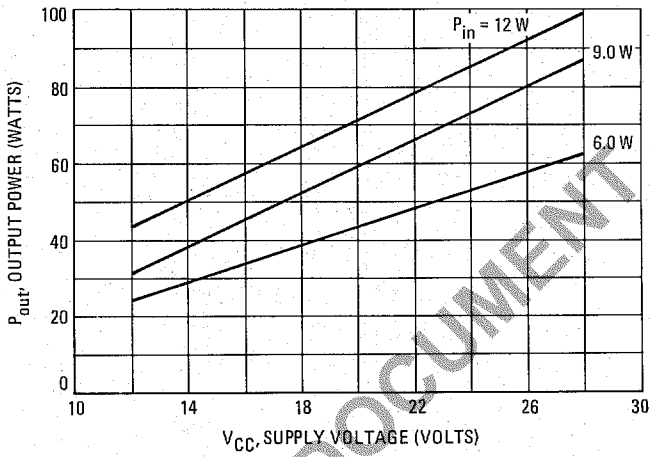


FIGURE 5 – OUTPUT POWER versus SUPPLY VOLTAGE
f = 400 MHz

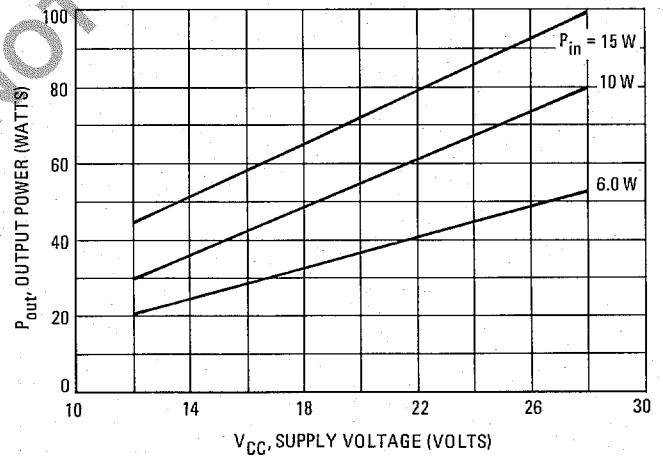


FIGURE 6 – OUTPUT POWER versus INPUT POWER

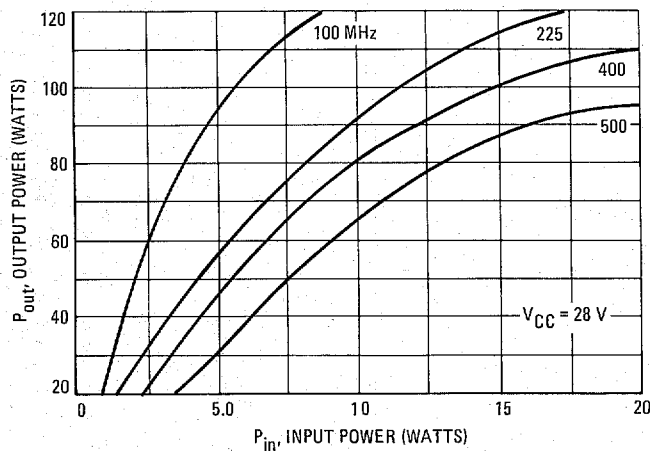
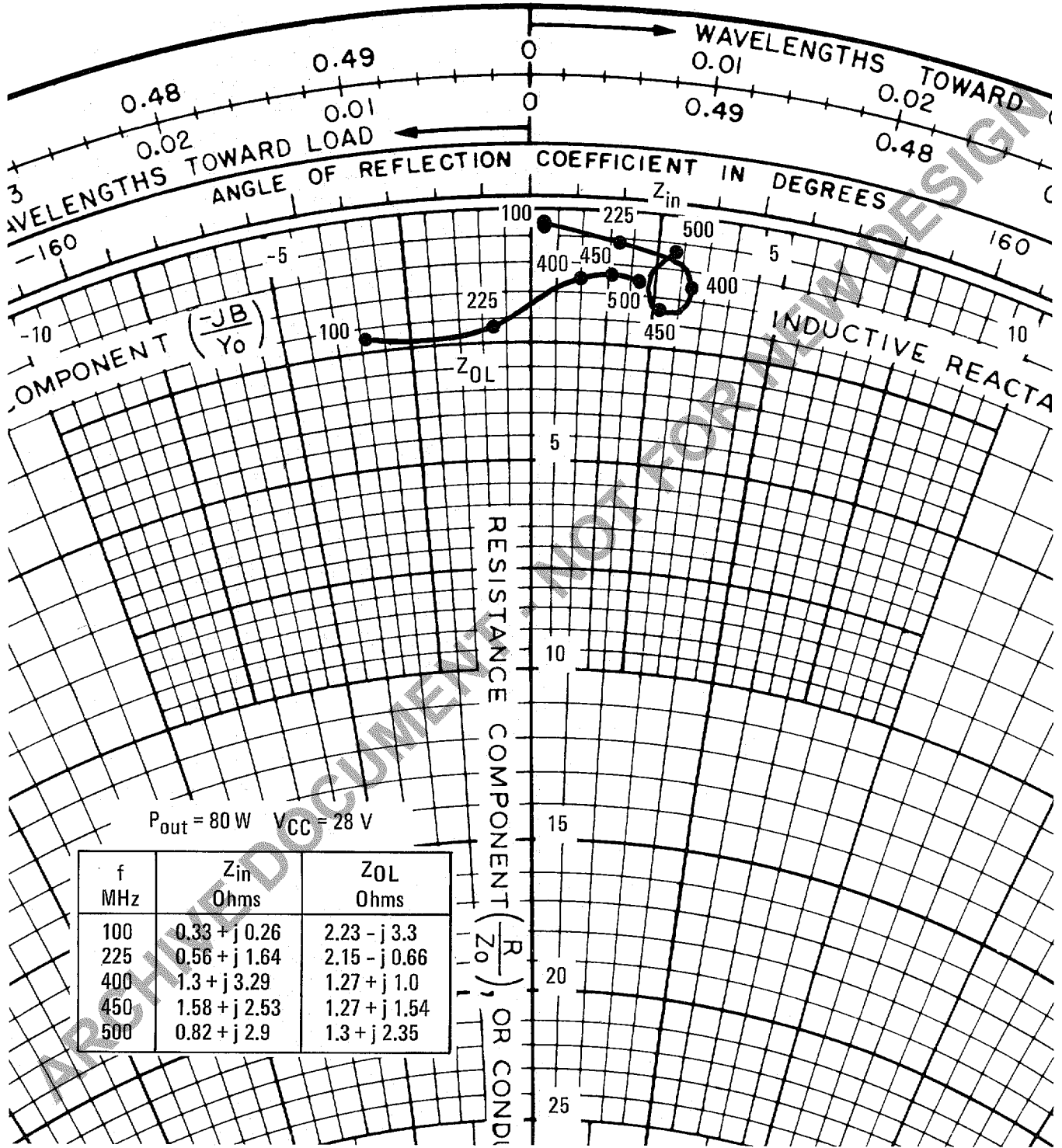


FIGURE 7 - SERIES EQUIVALENT INPUT-OUTPUT IMPEDANCE



$P_{out} = 80 W$ $V_{CC} = 28 V$

f MHz	Z_{in} Ohms	Z_{OL} Ohms
100	$0.33 + j 0.26$	$2.23 - j 3.3$
225	$0.56 + j 1.64$	$2.15 - j 0.66$
400	$1.3 + j 3.29$	$1.27 + j 1.0$
450	$1.58 + j 2.53$	$1.27 + j 1.54$
500	$0.82 + j 2.9$	$1.3 + j 2.35$



MOTOROLA Semiconductor Products Inc.

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